HALOGEN

FREE



Vishay Semiconductors

Ultrafast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS									
I _{F(AV)}	15 A								
V _R	600 V								
V _F at I _F	1.1 V								
t _{rr} (typ.)	24 ns								
T _J max.	175 °C								
Package	TO-220AC 2L								
Circuit configuration	Single								

FEATURES

- Low forward voltage drop
- Ultrafast soft recovery time
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

State of the art, ultralow V_F , soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Peak repetitive reverse voltage	V _{RRM}		600	V						
Average rectified forward current in DC	I _{F(AV)}	T _C = 151 °C	15	15 A						
Non-repetitive peak surge current	tive peak surge current I _{FSM} T _J = 25 °C 160									
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	600	-	-	.,				
Forward voltage	V _F	I _F = 15 A	-	1.35	1.9	V				
Forward voitage		I _F = 15 A, T _J = 150 °C	-	1.1	1.3					
Reverse leakage current	I _R	$V_R = V_R$ rated	-	0.01	15	μA				
neverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$ - 20		200	μΑ					
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH				



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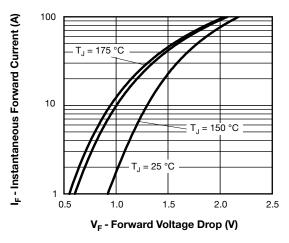
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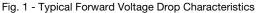
DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 10$	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			28			
Dovorno rogovery timo		$I_F = 15 \text{ A}, dI_F/dt = 10$	-	36	47				
Reverse recovery time	t _{rr}	T _J = 25 °C		-	40	-	ns		
		T _J = 125 °C		-	87	-			
Dools was a series a series and	,	T _J = 25 °C	$I_F = 15 \text{ A},$	-	5	-	- A		
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 200 A/\mu s,$ $V_B = 390 V$	-	9	-			
Devices receives above	0	T _J = 25 °C] "	-	107	-			
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	430	-	nC		
Reverse recovery time	t _{rr}		I _F = 15 A,	-	53	-	ns		
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 \text{ A/µs},$ $V_B = 390 \text{ V}$	-	25	-	Α		
Reverse recovery charge	Q _{rr}		-	730	-	nC			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C				
Thermal resistance, junction-to-case	R _{thJC}		ı	1.2	1.4					
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70	°C/W				
Typical thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth and greased		0.5	-					
Weight			-	2	-	g				
vveignt			-	0.07	-	OZ.				
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-220AC 2L	ETU1506							



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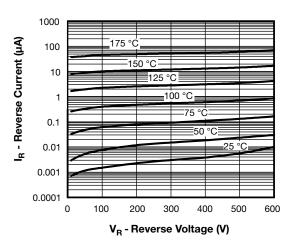


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

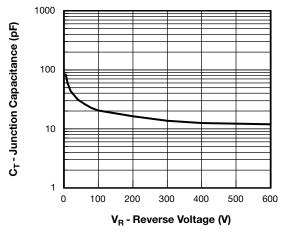


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

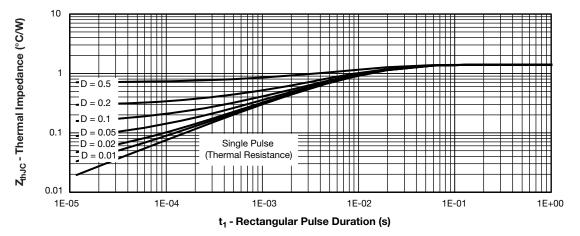


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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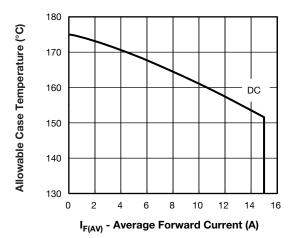
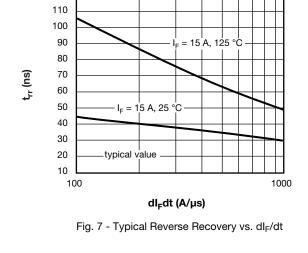


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current



120

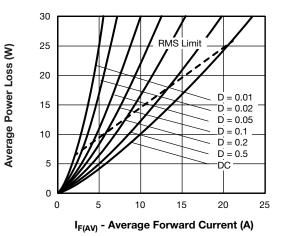


Fig. 6 - Forward Power Loss Characteristics

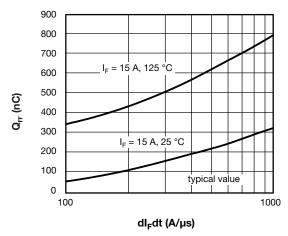
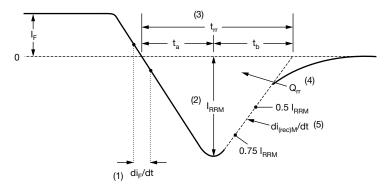


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

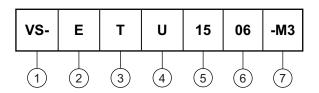
Fig. 9 - Reverse Recovery Waveform and Definitions



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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Circuit configuration:

E = single

3 - T = 2L TO-220AC

U = hyperfast recovery time

5 - Current code: 15 = 15 A

6 - Voltage code: 06 = 600 V

7 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-ETU1506-M3	50	Antistatic plastic tubes							

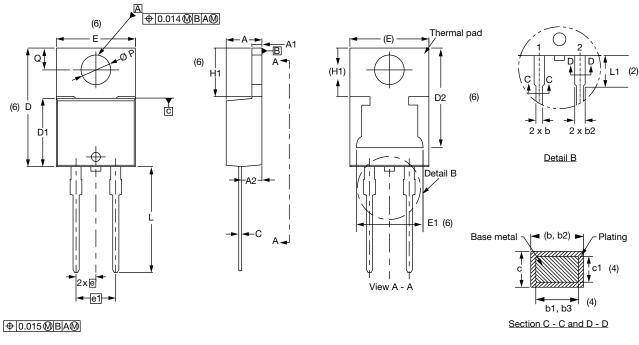
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?96156						
Part marking information	www.vishay.com/doc?95391						
SPICE model	www.vishay.com/doc?96130						



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TO-220AC 2L

DIMENSIONS in millimeters and inches



Lead tip

Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIN	IETERS	INC	HES	NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183			D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055			E	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355							•	

Notes

- $^{(1)}$ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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